# **PRODUCT SPECIFICATION**





- < >> Preliminary Specification
- < ◆> Finally Specification

	CUSTOMER'	S APPROVAL
CUSTOMER:		
SIG	NATURE:	DATE:

APPROVED	PM	PD	PREPARED
ВҮ	REVIEWED	REVIEWED	BY
TFT S. G. H 20220818			TFT C. L 20220818

knitter-switch

# **Revision History**

Revision	Date	Originator	Detail	Remarks
1.0	2022.06.21	LQ	Initial Release	
1.1	2022.08.18	CL	Add Weight Add Current Consumption Add CIE Value	P4 P5 P6

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# 1. General Description

The specification is a transmissive type color active matrix liquid crystal display (LCD) which uses amorphous thin film transistor (TFT) as switching devices. This product is composed of a TFT-LCD panel, driver ICs and a backlight unit.

### 2. Module Parameter

Features	Details	Unit
Display Size(Diagonal)	6.9"	
LCD type	IPS TFT	
Display Mode	Transmissive /Normally black	
Resolution	280 RGB x 1424	Pixels
View Direction	FULL VIEW	Best Image
Module Outline	38.20(H) x 181.47 (V) x 3.40 (T) (Note1)	mm
Active Area	33.60 (H) x 170.88 (V)	mm
Pixel Size	120.0 (H) x 120.0 (V)	um
Pixel Arrangement	RGB Vertical Stripe	
Display Colors	16.7M	
Interface	2 Lane MIPI	
With or without touch panel	Without	
Driver IC	FL7703NI	-
Operating Temperature	-20~70	°C
Storage Temperature	-30~80	°C
Weight	43	g

Note 1: Exclusive hooks, posts, FFC/FPC tail etc.

# 3. Absolute Maximum Ratings

GND=0V, Ta=25°C

Item	Symbol	Min.	Max.	Unit
Supply Voltage	VDDA	-0.3	6.6	V
Supply Voltage	VDDIO	-0.3	5.6	V
Storage temperature	T <sub>STG</sub>	-30	+80	°C
Operating temperature	T <sub>OP</sub>	-20	+70	°C

Note 1: If Ta below 50°C, the maximal humidity is 90%RH, if Ta over 50°C, absolute humidity should be less than 60%RH.

Note 2: The response time will be extremely slow when the operating temperature is around -10 $^{\circ}$ C, and the back ground will become darker at high temperature operating.

# 4. DC Characteristics

Item		Symbol	Min.	Тур.	Max.	Unit
Cupply Voltage		VDDA	2.5	2.8	3.3	V
Supply Voltage		VDDIO	1.65	1.8	3.3	V
Logic High level input volta	Logic High level input voltage		0.7*VDDIO	-	VDDIO	mV
Logic Low level input voltage		V <sub>IL</sub>	GND	-	0.3*VDDIO	mV
Logic High level Output voltage		V <sub>OH</sub>	0.8*VDDIO	-	VDDIO	mV
Logic Low level Output voltage		V <sub>OL</sub>	GND	-	0.2*VDDIO	mV
Current Consumption	Logic	IVDDA+		52		mA
All white	Analog	I <sub>VDDIO</sub>	_	52	_	ША

# 5. Backlight Characteristic

# 5.1. Backlight Characteristic

Item	Symbol	Condition	Min.	Тур.	Max.	Unit
Forward Voltage	VF	Ta=25 °C, I <sub>F</sub> =40mA/LED	21.0	25.6	27.5	V
Forward Current	lF	Ta=25 °C, V <sub>F</sub> =3.2V/LED	1	40	-	mA
Power dissipation	Po		-	1024	-	mW
Uniformity	Avg		80	-	-	%
LED working life(25℃)	-		-	30,000	-	Hrs
Drive method	Constant current					
LED Configuration		8 White LEDs (8 L	EDs in on	e string)		

Note1: LED life time defined as follows: The final brightness is at 50% of original brightness.

The environmental conducted under ambient air flow, at Ta=25 $\pm2$  °C,60%RH $\pm5$ %, I<sub>F</sub>=40mA/LED.

# 5.2. Backlight Characteristic



# 6. Optical Characteristics

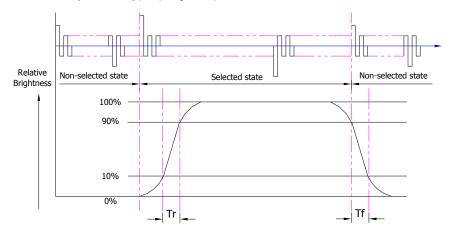
# 6.1. Optical Characteristics

Ta=25°C, VDDA=2.8V

	Item		Symbol	Condition	S	pecification	on	Unit	
	iten		Symbol	Condition	Min.	Тур.	Max.	Unit	
	Luminance on								
	$TFT(I_f$ =40r	DmA/LED)	Normally	328	410	-	cd/m²		
ode	Contrast ratio(See 6.3)		CR	viewing angle	900	1200	-		
Backlight On (Transmissive Mode)	Response time (See 6.2)		TR+TF	$\theta x = \phi Y = 0^{\circ}$	·		-	35	ms
E i		Bod	XR		0.591	0.641	0.691		
ans	Chromaticity Green	Reu	YR		0.278	0.328	0.378		
Ë		Croon	XG		0.269	0.319	0.369		
o n		Gieen	YG		0.566	0.616	0.666		
ļ <u>t</u>	Transmissive	Blue	Хв		0.084	0.134	0.184		
<u> </u>	(See 6.5)	blue	YB		0.025	0.075	0.125		
3ac		\ A / I= ' ( =	Xw		0.223	0.273	0.323		
"		White	Yw		0.240	0.290	0.340		
	Viewing Angle Horizont	l lowi-outol	θx+		80	85	-		
			Өх-	Center CR≥10	80	85	-	Dog	
	(See 6.4)	Vertical	φY+	Center CR210	80	85	-	Deg.	
		VEHILLAI	φY-		80	85	-		
	NTSC Ratio	(Gamut)			60	65	-	%	

# 6.2. Definition of Response Time

### 6.2.1. Normally Black Type (Negative)

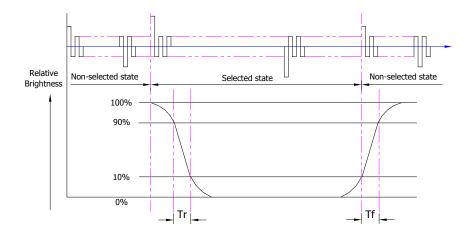


Tr is the time it takes to change form non-selected stage with relative luminance 10% to selected state with relative luminance 90%;

Tf is the time it takes to change from selected state with relative luminance 90% to non-selected state with relative luminance 10%.

Note: Measuring machine: LCD-5100

### 6.2.2. Normally White Type (Positive)



Tr is the time it takes to change form non-selected stage with relative luminance 90% to selected state with relative luminance 10%;

Tf is the time it takes to change from selected state with relative luminance 10% to non-selected state with relative luminance 90%;

Note: Measuring machine: LCD-5100 or EQUI

### 6.3. Definition of Contrast Ratio

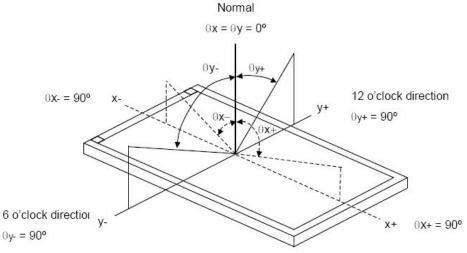
Contrast is measured perpendicular to display surface in reflective and transmissive mode.

The measurement condition is:

Measuring Equipment	Eldim or Equivalent
Measuring Point Diameter	3mm//1mm
Measuring Point Location	Active Area centre point
Test nettern	A: All Pixels white
Test pattern	B: All Pixel black
Contrast setting	Maximum

Definitions: CR (Contrast) = Luminance of White Pixel / Luminance of Black Pixel

# 6.4. Definition of Viewing Angles

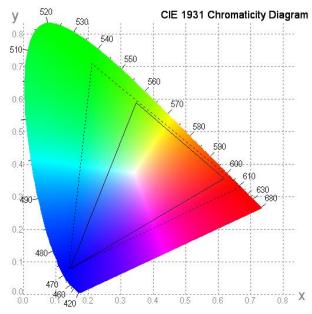


Measuring machine: LCD-5100 or EQUI

### 6.5. Definition of Color Appearance

R,G,B and W are defined by (x,y) on the IE chromaticity diagram NTSC=area of RGB triangle/area of NTSC triangleX100%

Measuring picture: Red, Green, Blue and White (Measuring machine: BM-7)

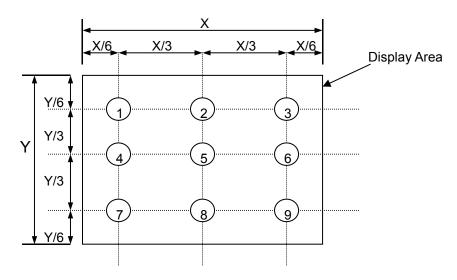


### 6.6. Definition of Surface Luminance, Uniformity and Transmittance

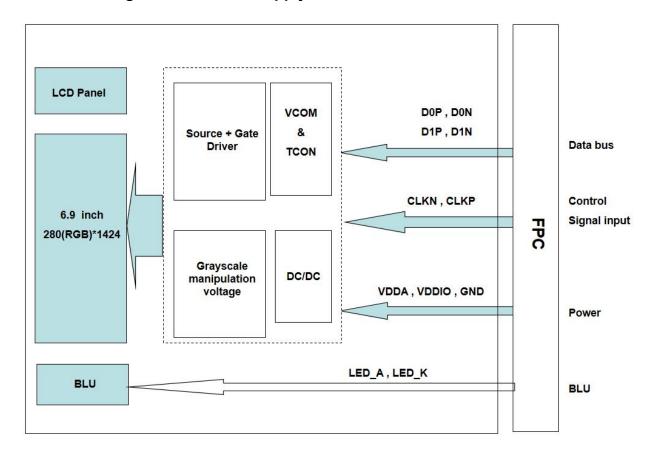
Using the transmissive mode measurement approach, measure the white screen luminance of the display panel and backlight.

- 6.6.1. Surface Luminance:  $L_V$  = average ( $L_{P1}$ : $L_{P9}$ )
- 6.6.2. Uniformity = Minimal  $(L_{P1}:L_{P9})$  / Maximal  $(L_{P1}:L_{P9})$  \* 100%
- 6.6.3. Transmittance =  $L_V$  on LCD /  $L_V$  on Backlight \* 100%

Note: Measuring machine: BM-7



# 7. Block Diagram and Power Supply

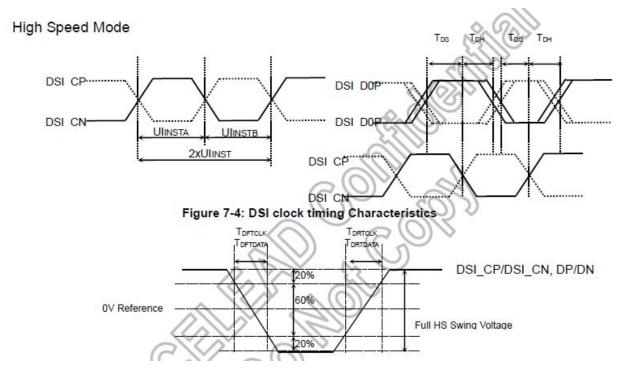


# 8. Interface Pins Definition

No.	Symbol	Function	Remark
1	GND	Ground	
2	VDDA	A power supply for analog circuit	
3	VDDIO	A power supply for the logic power and I/O circuit	
4	GND	Ground	
5	D0N	MIPI data Input	
6	D0P	MIPI data Input	
7	GND	Ground	
8	D1N	MIPI data Input	
9	D1P	MIPI data Input	
10	GND	Ground	
11	CLKN	MIPI clock Input	
12	CLKP	MIPI clock Input	
13	GND	Ground	
14	LED_A	Led anode	
15	LED_K	Led cathode	

# 9. AC Characteristics

# 9.1. DSI Interface Timing Characteristics



C:I	14	Complete	Sp	Spec.		
Signal	Item	Symbol		Тур.	Max.	Unit
DSI CP/	Double UI instantaneous	2xUinst	4LANE: 3.30 3LANE: 2.85 @ VDDD=1.8V	-	25	ns
DSI_CN	UI instantaneous	UINSTA UINSTB	4LANE: 1.67 3LANE: 1.43 @ VDDD=1.8V	-	12.5	ns
DP/DN	Data to clock setup time	T <sub>DS</sub>	0.15xUI	н	1.5	ps
DEIDIN	Data to clock hold time	T <sub>DH</sub>	0.15xUI	-	-	ps
DSI CP/	Differential rise time for clock	TORTCLK	150		0.3UI	ps
DSI_CN	Differential fall time for clock	Toftclk	150	5	0.3UI	ps
DP/DN	Differential rise time for data	TORTDATA	150	-	0.3UI	ps
DEIDIN	Differential fall time for data	TOFTDATA	150	2	0.3UI	ps

### Low Power Mode

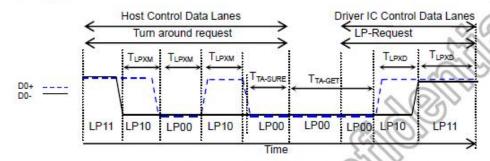
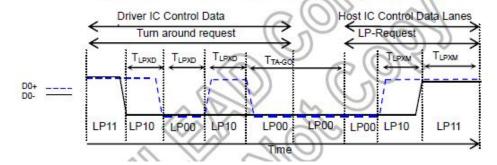
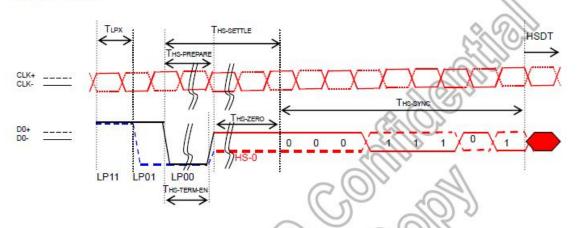


Figure 7-6: BTA from HOST to Display Module Timing

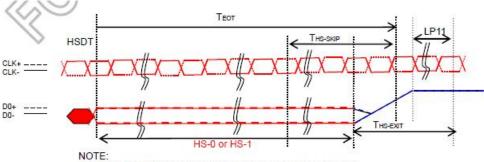


Cinnal	Item	Symbol	Spec.			11.29
Signal			Min.	Тур.	Max.	Unit
	Length of LP-00/LP01/LP10/LP11 Host→ Display module	TLPXM	50	67	_	ns
OSI DOP/	Length of LP-00/LP01/LP10/LP11 Display module → Host	TLPXD	50	8 <del>7</del> 8	3 <del>-</del> 2	ns
OSI_DOP	Time-out before the MPU start driver	T <sub>TA-SURE</sub>	TLPXD	(23)	2xTLPXD	ns
**************************************	Time to drive LP-00 by display module	T <sub>TA-GET</sub>	5xTLPXD	(5)	272	ns
	Time to drive LP-00 after turnaround request Host	TTAGO	4xTLPXD	848	-	ns

# **DSI BURSTS**

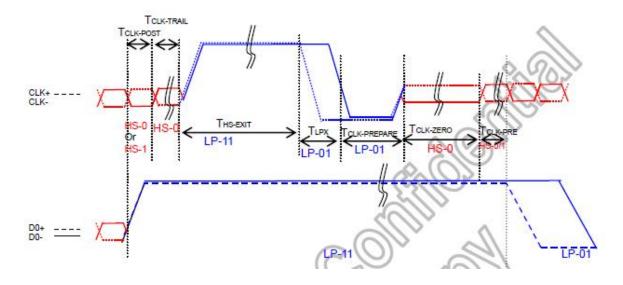


Signal	144	Countries I	Spec.			Hade
	ltem	Symbol	Min.	Тур.	Max.	Unit
	Length of LP-00/LP01/LP10/LP11	TLPX	50	-	2	ns
DOL DOD!	Time to Driver LP-00 to prepare for HS transmission	THS-PREPARE	40+4UI		85+6UI	ns
DSI_DUP	Time to enable data receiver line termination	THS-TERM-EN	-	**	35+4xUI	ns
	Time to drive LP-00 by display module	TTA-GET	5xTLPXD	<u> 10</u> 7	2 .	ns
	Time to drive LP-00 after turnaround request Host	TTAGO	4xTLPXD	=	=	ns



NOTE:
If the last bit is HS-0, the transmitter changes from HS-0 to HS-1
If the last bit is HS-0, the transmitter changes from HS-1 to HS-0

Cianal	la	Symbol	Spec.			1144
Signal	ltem		Min.	Тур.	Max.	Unit
DSI_D0P/ DSI_D0P	Transition Period of E01	THS-SKIP	40	S <b>E</b> S	55+4xUI	ns
	Time to Driver LP-11 after HS Burst	THS-EXIT	100	133	453	ns



0:1	Item	0 1	Spec.			
Signal		Symbol	Min.	Тур.	Max.	Unit
	Time that the MCU shall continue sending HS clock after the last associated Data Lane has transitioned to LP mode		60+52xUI	2	72	ns
	Time to drive HS differential state after last payload clock bit of a HS transmission burst	TCLK-TRAIL	60	2	42	ns
	Time to drive LP-11 after HS burst	THS-EXIT	100	-		ns
DSI_CP/	Time to drive LP-00 to prepare for HS transmission	TCLK-PREPARE	38	2	95	ns
DSI_CN	Time-out at Clock Lane Display Module to enable HS Termination	TCLK-TERM-EN	-	-	38	ns
	Minimum lead HS-0 drive period before starting Clock	TCLK-PREPARE + TCLK-ZERO	300	15	(ST.)	ns
	Time that the HS clock shall be driven prior to any associated data Lane beginning the transition from LP to HS mode		8xUI			

# 10. Quality Assurance

### 10.1.Purpose

This standard for Quality Assurance assures the quality of LCD module products supplied to customer.

#### 10.2. Standard for Quality Test

10.2.1. Sampling Plan:

GB2828.1-2012

Single sampling, general inspection level II

10.2.2. Sampling Criteria:

Visual inspection: AQL 1.5

Electrical functional: AQL 0.65.

10.2.3. Reliability Test:

Detailed requirement refer to Reliability Test Specification.

### 10.3. Nonconforming Analysis & Disposition

- 10.3.1. Nonconforming analysis:
  - 10.3.1.1. Customer should provide overall information of non-conforming sample for their complaints.
  - 10.3.1.2. After receipt of detailed information from customer, the analysis of nonconforming parts usually should be finished in one week.
  - 10.3.1.3. If cannot finish the analysis on time, customer will be notified with the progress status.
- 10.3.2. Disposition of nonconforming:
  - 10.3.2.1. Non-conforming product over PPM level will be replaced.
  - 10.3.2.2. The cause of non-conformance will be analyzed. Corrective action will be discussed and implemented.

### 10.4. Agreement Items

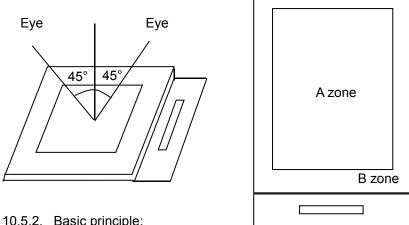
Shall negotiate with customer if the following situation occurs:

- 10.4.1. There is any discrepancy in standard of quality assurance.
- 10.4.2. Additional requirement to be added in product specification.
- 10.4.3. Any other special problem.

### 10.5. Standard of the Product Visual Inspection

- 10.5.1. Appearance inspection:
  - 10.5.1.1. The inspection must be under illumination about  $1000 1500 \, lx$ , and the distance of view must be at  $30 \, cm \pm 2 \, cm$ .
  - 10.5.1.2. The viewing angle should be 45° from the vertical line without reflection light or follows customer's viewing angle specifications.

10.5.1.3. Definition of area: A Zone: Active Area, B Zone: Viewing Area,



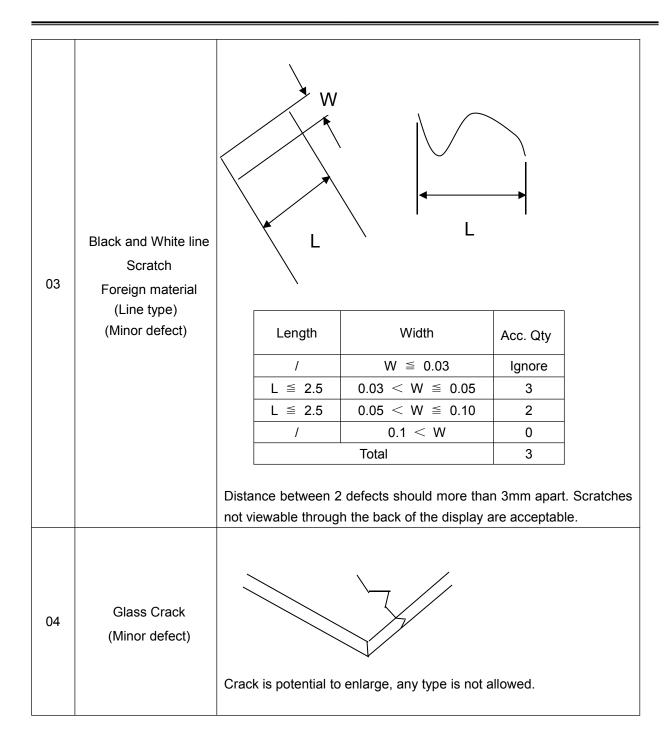
10.5.2. Basic principle:

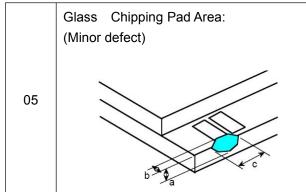
10.5.2.1. A set of sample to indicate the limit of acceptable quality level must be discussed by both us and customer when there is any dispute happened.

10.5.2.2. New item must be added on time when it is necessary.

# 10.6.Inspection Specification

No.	Item	Criteria (Unit: mm)				
01	Black / White spot Foreign material (Round type) Pinholes Stain Particles inside cell. (Minor defect)	$\phi = (a + b)/2$ Distance between 2 of	Size	≤0.50 <φ	Acc. Igno N≤ 0	ore
02	Electrical Defect (Minor defect)	Display Area       Total         Bright dot       N≤2       N≤2         Dark dot       N≤4       N≤4         Total dot       N≤4       N≤4         Mura       Not visible through 5% ND filters.         Remark:       1. Bright dot caused by scratch and foreign object accords			<b>≤2 ≤4 ≤4</b> O filters.	Note 1 Note 2





Length and Width	Acc. Qty			
c > 3.0, b< 1.0	1			
c< 3.0, b< 1.0	3			
a <glass td="" thickness<=""></glass>				

	Glass Chipping Rear of Pad Area: (Minor defect)		
		Length and Width	Acc. Qty
06		c > 3.0, b< 1.0	1
		c< 3.0, b< 1.0	2
		c< 3.0, b< 0.5	4
	b	a <glass td="" thick<=""><td>kness</td></glass>	kness
	Glass Chipping Except Pad Area: (Minor defect)		
	(Willion defect)	Length and Width	Acc. Qty
		c > 3.0, b< 1.0	1
07		c< 3.0, b< 1.0	2
	b	c< 3.0, b< 0.5	4
		a <glass td="" thick<=""><td></td></glass>	
	a	a Glass IIIIo.	
	Glass Corner Chipping: (Minor defect)	Length and Width	Acc. Qty
08		c < 3.0, b< 3.0 a <glass td="" thick<=""><td>Ignore</td></glass>	Ignore
	ba		
	Glass Burr: (Minor defect)		
	/**************************************	Length	Acc. Qty
		F < 1.0	Ignore
09		Glass burr don't affect ass dimension.	

	FPC Defect:					
	(Minor defect)		49.4.5.4.4.4.4.4.4.49			
	a <u>-</u> ⊧ +-	_		10.1 Dent, pinhole width a <w 3.<="" td=""></w>		
10	$\mathbf{w} \longrightarrow 0$	←—	(w: circuitry width.	(w: circuitry width.)		
	" 7		10.2 Open circuit i	s unacceptable.		
			10.3 No oxidation,	contamination	and distortion.	
	a <del></del> -	<b></b>				
			Diameter	Acc. Qty		
	Dubble on Delevinos		φ≤0.20	Ignore		
11	Bubble on Polarizer		0.20 <φ≤0.30	4		
(Minor defec	(Minor defect)		0.30 <φ≤0.50	1		
			0.50 < φ	None		
					-	
			Diameter	Acc. Qty	]	
12	Dent on Polarizer		φ≤0.20	Ignore		
			0.20 <φ≤0.30	4		
	(Minor defect)		0.30 <φ≤0.50	1		
			0.50 < φ	None		
					J	
13	Bezel	13.1 No rust, di	stortion on the Bezel.			
		13.2 No visible	fingerprints, stains or otl	her contaminatio	on.	
		14.1 No distorti	on or contamination on I	PCB terminals.		
			nents on PCB must sai		nted on the	
14	PCB			me de decamer	nod on the	
		BOM/component layout.				
		14.3 Follow IPC	-A-000F.			
15	Soldering	Follow IPC-A-610C standard				
		The below defe	cts must be rejected.			
			rtical / horizontal segme	ent,		
		16.2 Abnormal Display.				
	Flootrical Defeat	16.3 No function				
16	Electrical Defect	16.4 Current ex	ceeds product specifica	tions.		
	(Major defect)	16.5 LCD viewi	ng angle defect.			
		16.6 No Backlig				
		16.7 Dark Back	light.			
		16.8 Touch Pan	el no function.			

Remark: LCD Panel Broken shall be rejected. Defect out of LCD viewing area is acceptable.

#### 10.7. Classification of Defects

- 10.7.1. Visual defects (Except no / wrong label) are treated as minor defect and electrical defect is major.
- 10.7.2. Two minor defects are equal to one major in lot sampling inspection.

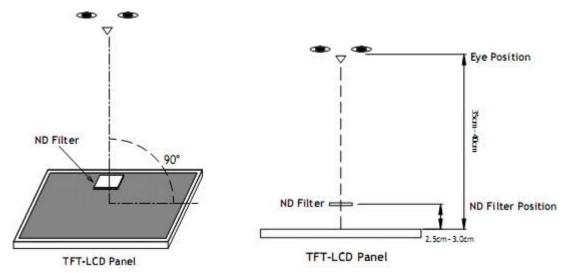
### 10.8.Identification/marking criteria

Any unit with illegible / wrong /double or no marking/ label shall be rejected.

### 10.9. Packing

- 10.9.1. There should be no damage of the outside carton box, each packaging box should have one identical label.
- 10.9.2. Modules inside package box should have compliant mark.
- 10.9.3. All direct package materials shall offer ESD protection.

**Note1**: Bright dot is defined as the defective area of the dot is larger than 50% of one sub-pixel area.



Bright dot: The bright dot size defect at black display pattern. It can be recognized by 2% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

Dark dot: Cyan, Magenta or Yellow dot size defect at white display pattern. It can be recognized by 5% transparency of filter when the distance between eyes and panel is  $350 \text{mm} \pm 50 \text{mm}$ .

**Note2:** Mura on display which appears darker / brighter against background brightness on parts of display area.

# 11. Reliability Specification

No	Item	Condition	Quantity	Criteria
1	High Temperature Operating	70℃, 96Hrs	2	GB/T2423.2 -2008
2	Low Temperature Operating	-20℃, 96Hrs	2	GB/T2423.1 -2008
3	High Humidity Storage	50℃, 90%RH, 96Hrs	2	GB/T2423.3 -2016
4	High Temperature Storage	80℃, 96Hrs	2	GB/T2423.2 -2008
5	Low Temperature Storage	-30℃, 96Hrs	2	GB/T2423.1 -2008
6	Thermal Cycling Test Storage	-20℃, 60min ~ 70℃, 60min, 20 cycles.	2	GB/T2423.22 -2012
7	Packing vibration	Frequency range:10Hz~50Hz Acceleration of gravity:5G X, Y, Z 30 min for each direction.	-	GB/T5170.14 -2009
8	Electrical Static Discharge	Air: $\pm$ 4KV 150pF/330 $\Omega$ 5 times	2	GB/T17626.2
	Liectrical Static Discharge	Contact: $\pm$ 2KV 150pF/330 $\Omega$ 5 times	2	-2018
9	Drop Test (Packaged)	Height:80 cm,1 corner, 3 edges, 6 surfaces.	-	GB/T2423.8 -1995

Note1. No defection cosmetic and operational function allowable.

Note2. Total current Consumption should be below double of initial value

# 12. Precautions and Warranty

### 12.1. Safety

- 12.1.1. The liquid crystal in the LCD is poisonous. Do not put it in your mouth. If the liquid crystal touches your skin or clothes, wash it off immediately using soap and water.
- 12.1.2. Since the liquid crystal cells are made of glass, do not apply strong impact on them. Handle with care.

#### 12.2. Handling

- 12.2.1. Reverse and use within ratings in order to keep performance and prevent damage.
- 12.2.2. Do not wipe the polarizer with dry cloth, as it might cause scratch. If the surface of the LCD needs to be cleaned, wipe it swiftly with cotton or other soft cloth soaked with petroleum IPA, do not use other chemicals.

### 12.3.Storage

- 12.3.1. Do not store the LCD module beyond the specified temperature ranges.
- 12.3.2. Strong light exposure causes degradation of polarizer and color filter.

### 12.4. Metal Pin (Apply to Products with Metal Pins)

12.4.1. Pins of LCD and Backlight

12.4.1.1. Solder tip can touch and press on the tip of Pin LEAD during the soldering

12.4.1.2. Recommended Soldering Conditions

Solder Type: Sn96.3~94-Ag3.3~4.3-Cu0.4~1.1

Maximum Solder Temperature: 370 ℃

Maximum Solder Time: 3s at the maximum temperature

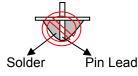
Recommended Soldering Temp: 350±20 ℃

Typical Soldering Time: ≤3s

12.4.1.3. Solder Wetting

Solder Pin Lead

Recommended



Not Recommended

#### 12.4.2. Pins of EL

12.4.2.1. Solder tip can touch and press on the tip of EL leads during soldering.

12.4.2.2. No Solder Paste on the soldering pad on the motherboard is recommended.

12.4.2.3. Recommended Soldering Conditions

Solder type: Nippon Alimit Leadfree SR-34, size 0.5mm

Recommended Solder Temperature: 270 ~ 290 ℃

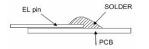
Typical Soldering Time: ≤2s

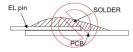
Minimum solder distance from EL lamp (body):2.0mm

12.4.2.4. No horizontal press on the EL leads during soldering.

12.4.2.5. 180° bend EL leads three times is not allowed.

#### 12.4.2.6. Solder Wetting





Recommended

Not Recommended

12.4.2.7. The type of the solder iron:





Recommended

Not Recommended

12.4.2.8. Solder Pad



### 12.5. Operation

- 12.5.1. Do not drive LCD with DC voltage
- 12.5.2. Response time will increase below lower temperature
- 12.5.3. Display may change color with different temperature
- 12.5.4. Mechanical disturbance during operation, such as pressing on the display area, may cause the segments to appear "fractured".
- 12.5.5. Do not connect or disconnect the LCM to or from the system when power is on.
- 12.5.6. Never use the LCM under abnormal condition of high temperature and high humidity.
- 12.5.7. Module has high frequency circuits. Sufficient suppression to the electromagnetic interface shall be done by system manufacturers. Grounding and shielding methods may be important to minimize the interference.
- 12.5.8. Do not display the fixed pattern for long time (we suggest the time not longer than one hour) because it will develop image sticking due to the TFT structure.

#### 12.6. Static Electricity

- 12.6.1. CMOS LSIs are equipped in this unit, so care must be taken to avoid the electro-static charge, by ground human body, etc.
- 12.6.2. The normal static prevention measures should be observed for work clothes and benches.
- 12.6.3. The module should be kept into anti-static bags or other containers resistant to static for storage.

#### 12.7. Limited Warranty

- 12.7.1. Our warranty liability is limited to repair and/or replacement. We will not be responsible for any consequential loss.
- 12.7.2. If possible, we suggest customer to use up all modules in six months. If the module storage time over twelve months, we suggest that recheck it before the module be used.
- 12.7.3. After the product shipped, any product quality issues must be feedback within three months, otherwise, we will not be responsible for the subsequent or consequential events.

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TBD

# 14. Outline Drawing

